

**A SYSTEM AND METHOD FOR ACHIEVING PLANAR ALIGNMENT
OF A SUBSTRATE DURING SOLDER BALL MOUNTING FOR USE IN
SEMICONDUCTOR FABRICATION**

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ABSTRACT

A system (10) and method (30) for precisely depositing a solder compound onto a substrate (18). The system (10) generally includes a receiving member (20) having a rotatable portion (21) adapted to receive a planar substrate (18), a horizontal member (12) for depositing solder balls (11) on the substrate (18), and a contact member (14), located between the receiving member (20) and horizontal member (12). The contact member comprises an aligner plate (14) having a pair of stoppers (15) protruding therefrom. Advantageously, pivotable portion (21) of the system (10) establishes the planarity of the substrate (18), with respect to the horizontal mount (12) allowing for the solder balls (11) to be mounted thereon, preventing the substrate (18) from being slightly misaligned, warped, and/or tilted.

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